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Orthogonal Processing: A New Strategy for Patterning Organic Electronics

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Organic Electronics

Will enable simple, low cost electronics and photonics

Will make dumb object smart

Will complement Si-based electronics

(+) Ease of processing

(+) Tunability of electronic properties

(+) Integration with biological systems

(-) Low-end performance

(-) Lifetime

OTFTs

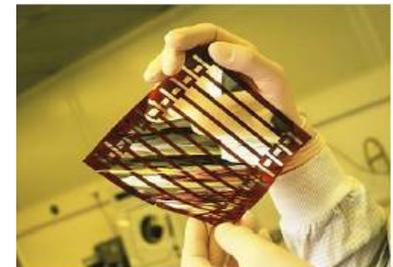


DuPont

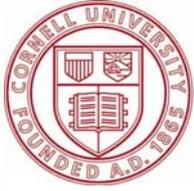
OLEDs



OPVs



Siemens



Outline

- **Patterning issues in organic electronics?**
- ***Orthogonal Processing* employing**
 - **Supercritical carbon dioxide**
 - **Hydrofluoroethers and tuned fluorinated materials**
- **Applications and possibilities**



Overview on Patterning of Solution Processable Organic Materials

technique	resolution	materials compatibility
photolithography	30 nm	photoresists, functional organics
inkjet printing	10-20 μm	organic conductors, low molecular weight polymers, wax, others
soft printing	0.1-2 μm	SAMs, thin metals, organic and inorganic semiconductors
imprint lithography	<10 nm	moldable resists, functional organics
capillary molding	2-5 μm	resists, low-viscosity inks, functional organics
laser imaging	5 μm	organic conductors, semiconductors and electroluminescent materials
embossing	1 nm	moldable resists, functional organics

E. Menard, *et al.*, *Chem. Rev.* 2007, 107, 1117.
 J. R. Sheats, *J. Mater. Res.* 2004, 19, 1974.

Patterning by Photolithography

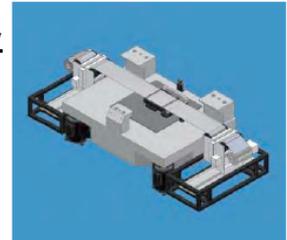
Advantages of photolithography

- Long history in Si industry
 - Optimized Process
 - Experienced operators
 - Cheaper depreciated equipment
- Parallel process
- Large area
- High Resolution
- Good registration (alignment between layers)

Precision Lithography: Capability

AzoresCorp, 2006

- Based on proven FPD stepper
- 8" width, can handle up to 24" with new chucks
- g-line (436 nm)
- 4 μm L/S
- 230 to 760 mm/min
- 400 ppm distortion compensation
- Requires hole-punch pattern for pre-alignment:



CAMM

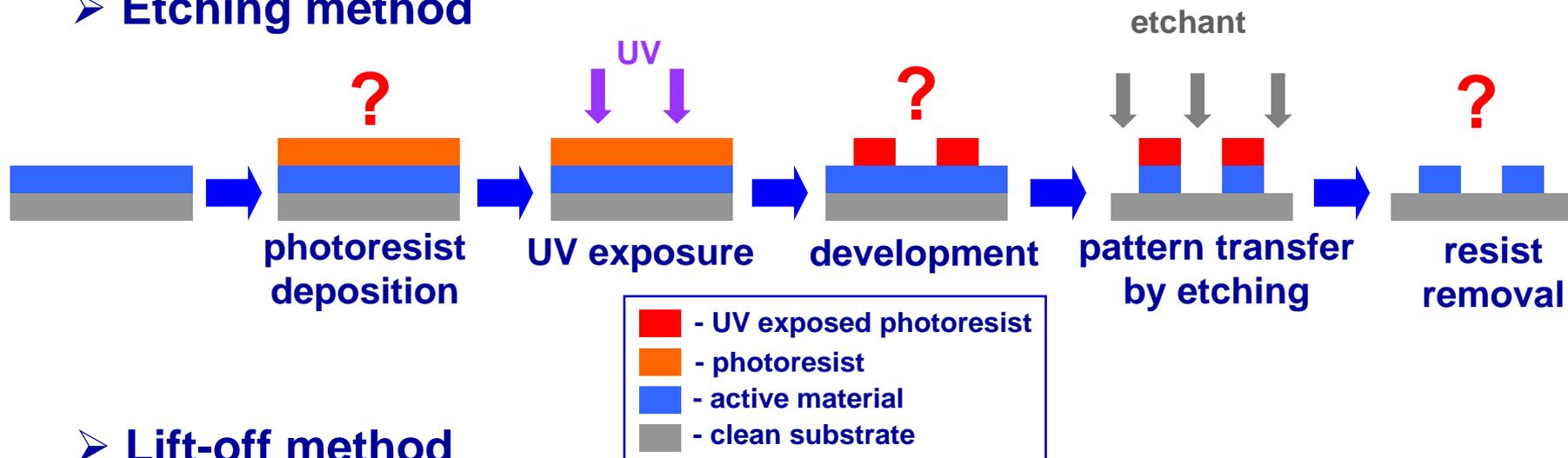


USD C

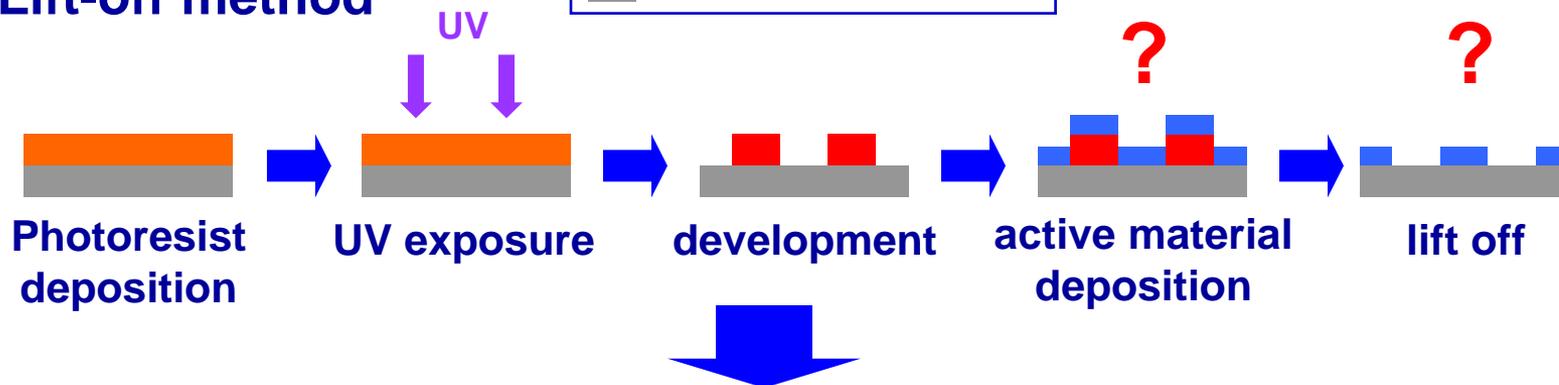
But... Chemical compatibility issues between process chemicals and organic electronic materials!

Problems in Photolithographic Patterning of Organic Materials

➤ Etching method



➤ Lift-off method



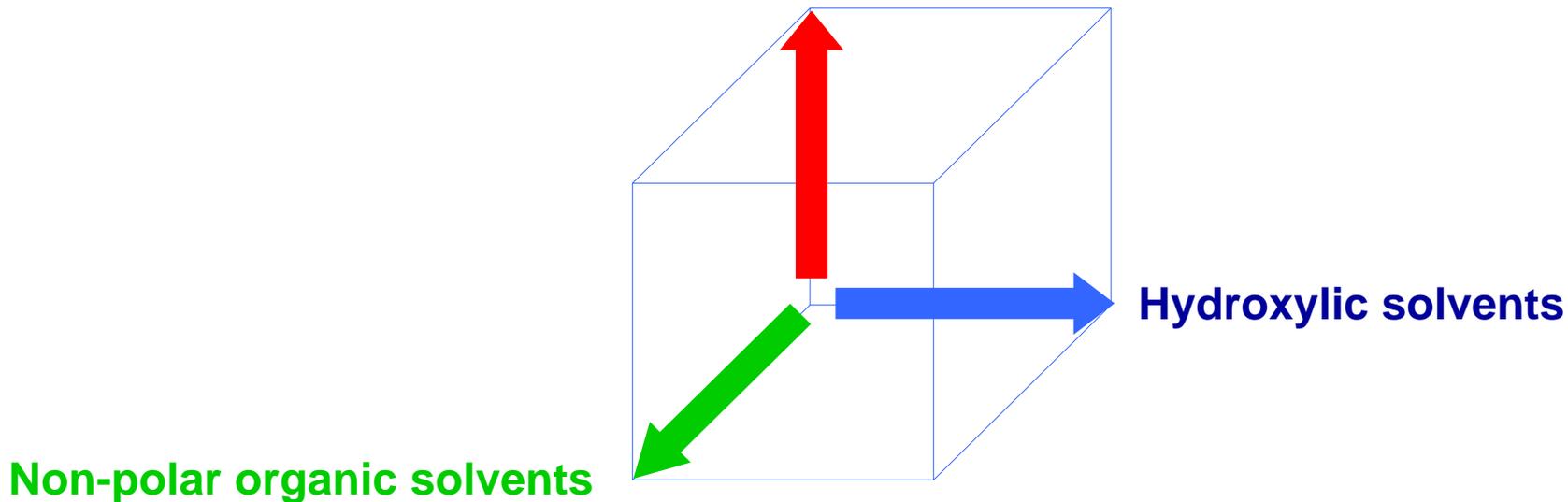
Development of lithographic conditions in chemically non-damaging solvent system

Orthogonal Patterning

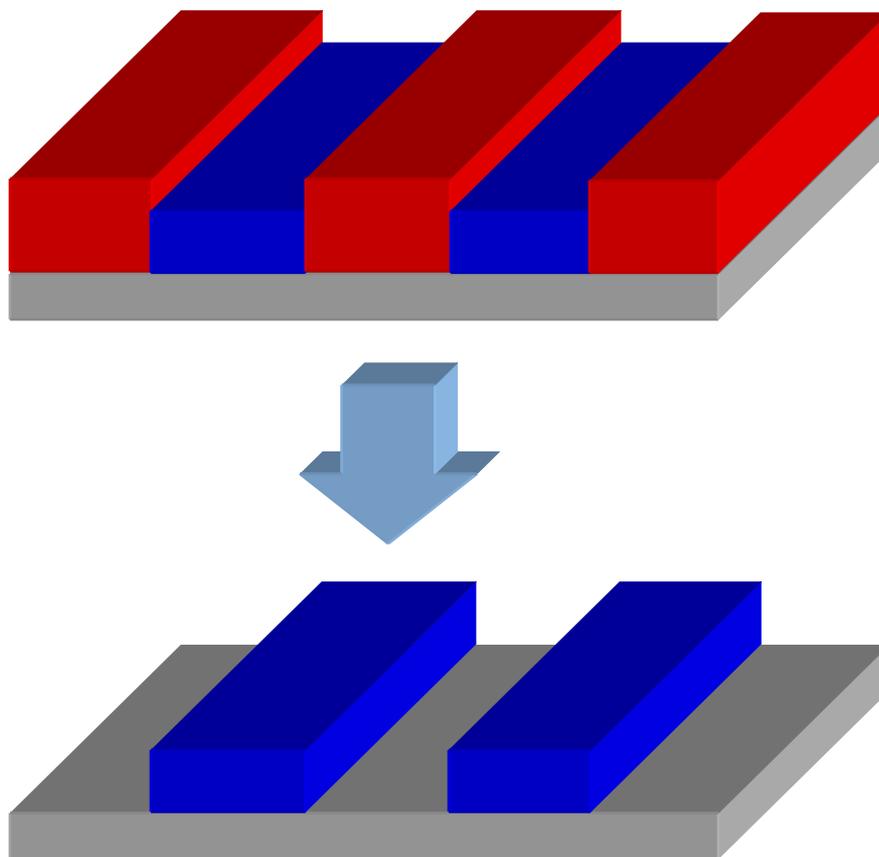
Research Objectives

To develop processes and materials for the fabrication of organic/flexible electronic devices employing chemically benign, environmentally-friendly process solvents

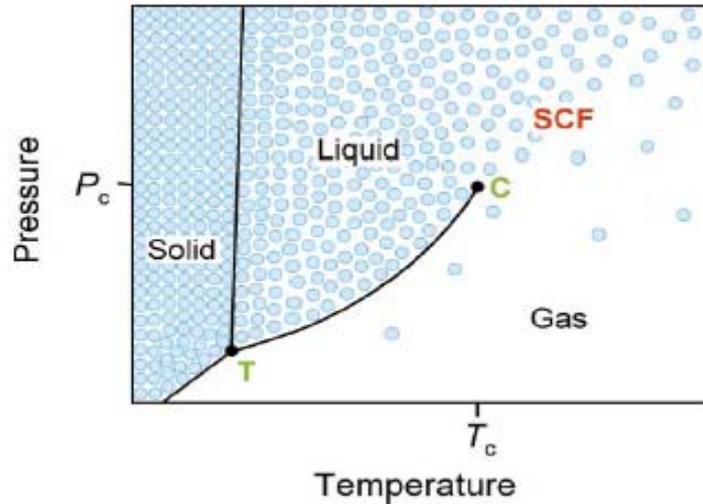
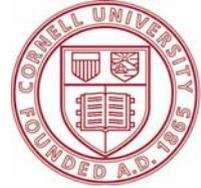
Orthogonal solvents
(scCO₂ & fluoros liquids)



- ✓ **Patterning Organic Electronic Materials** employing **Fluorinated Photoresists** in Hydrofluoroethers



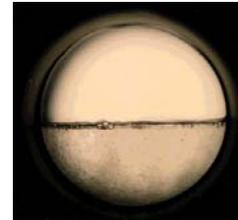
Supercritical Carbon Dioxide (scCO₂)



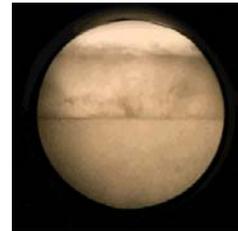
($T_c = 31.1\text{ }^\circ\text{C}$, $P_c = 72.8\text{ bar}$)

J. Mater. Chem. 2000, **10**, 207.

- Most non-fluorinated materials are stable in scCO₂
- Environmentally safe
- Cheap and readily available



Below critical point
- separate liquid and gas phases



Near critical point
- meniscus begins to fade



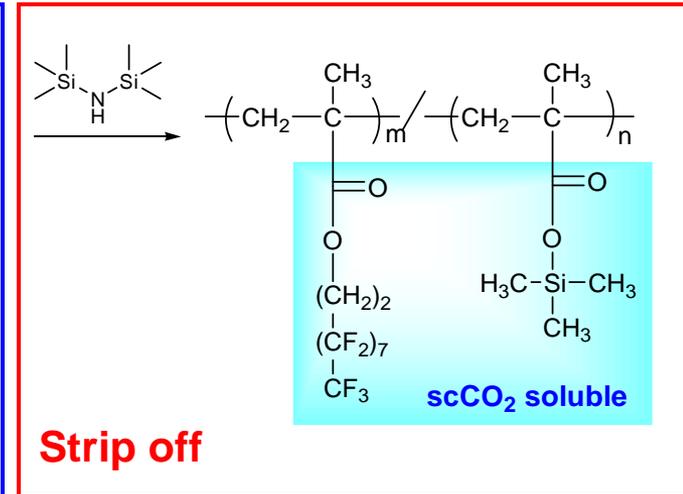
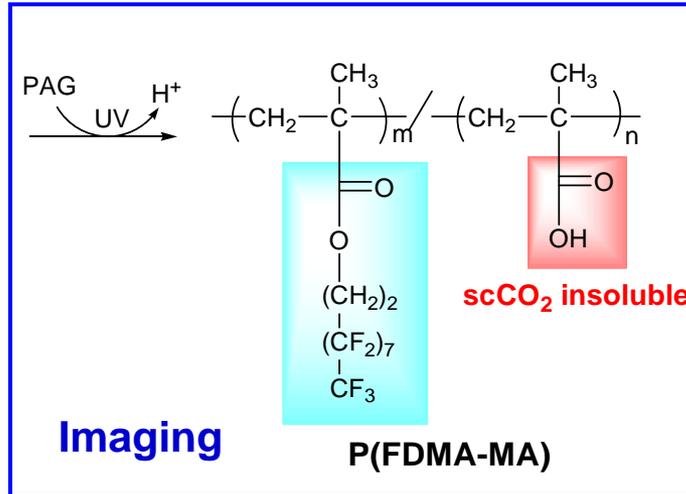
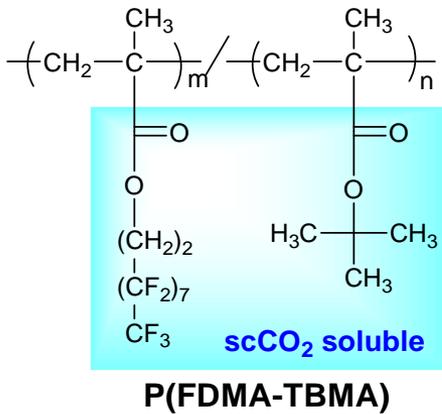
Above critical point
- no meniscus, homogeneous phase

J. Chem. Soc., Perkin Trans. 1, 2001, 917.

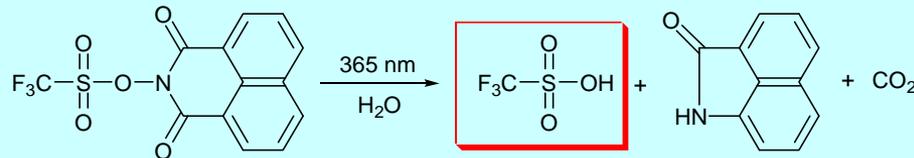
scCO₂ is promising to develop photoresist patterns!

Photoresist Processable in scCO₂

Mechanism



Acid generation from PAG

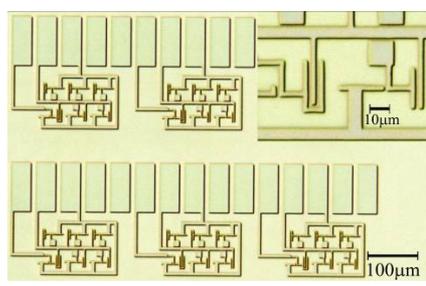


Chemical Physics Letters, 2007, **443**, 323.

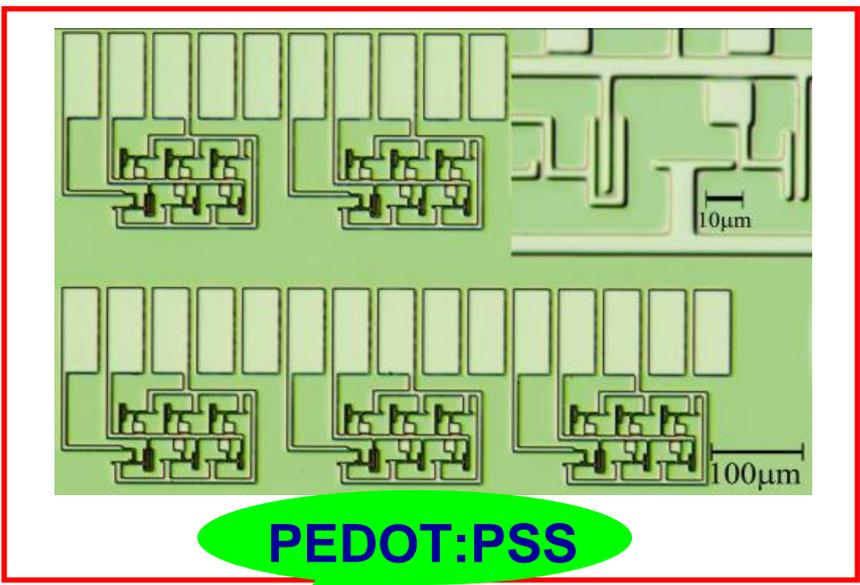


Lithographic Evaluation of Resist

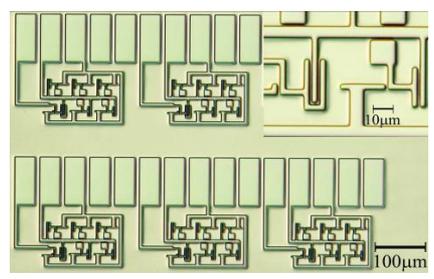
Good adhesion and pattern development on PEDOT:PSS film



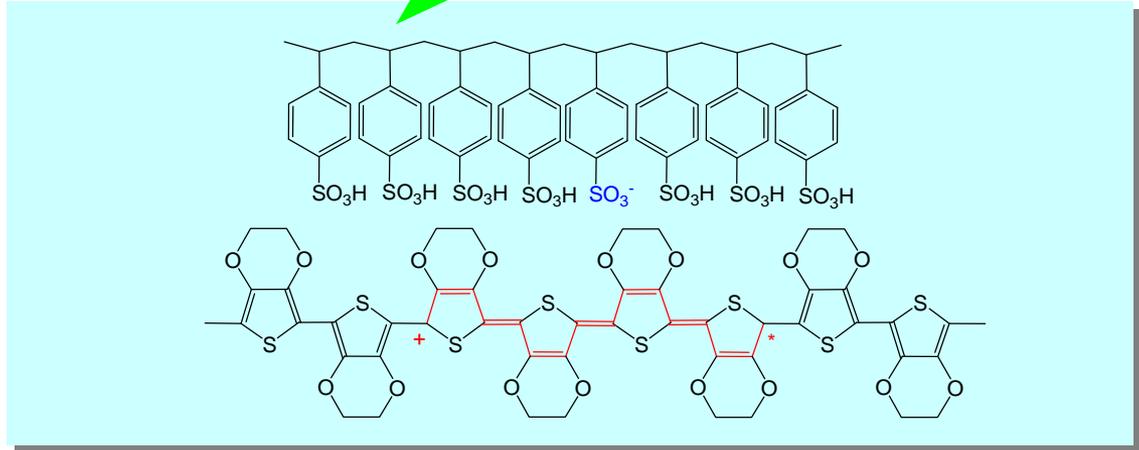
Glass



PEDOT:PSS

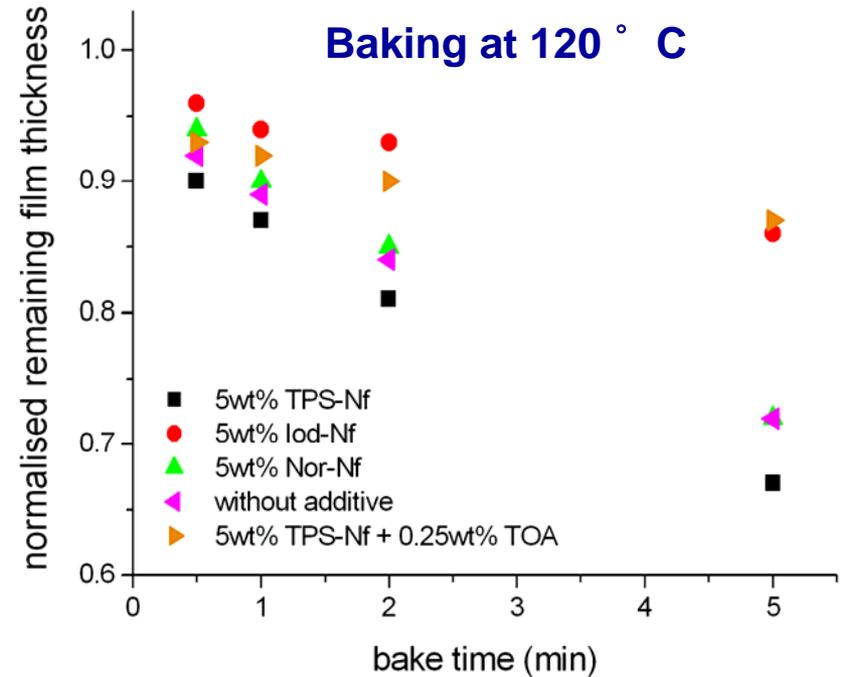
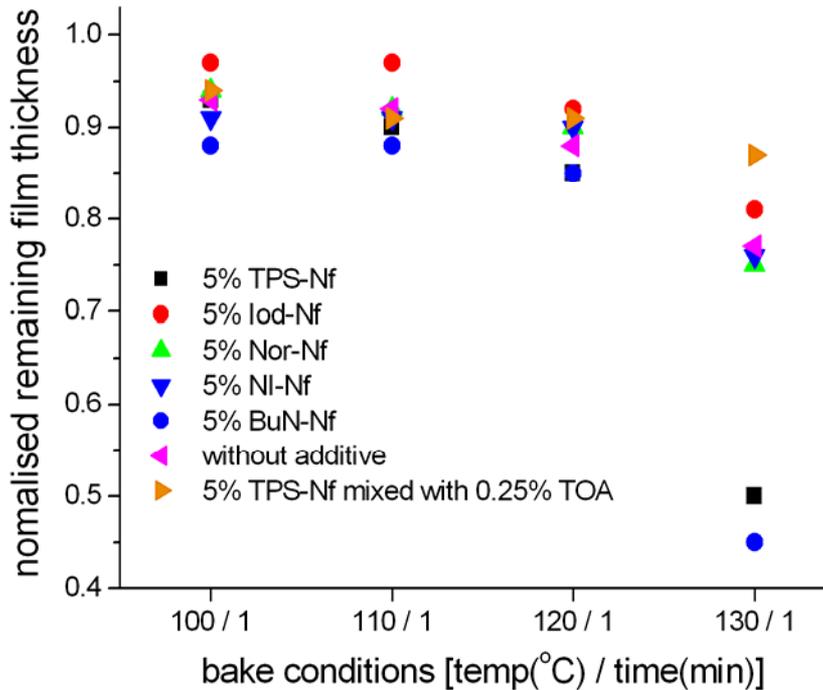
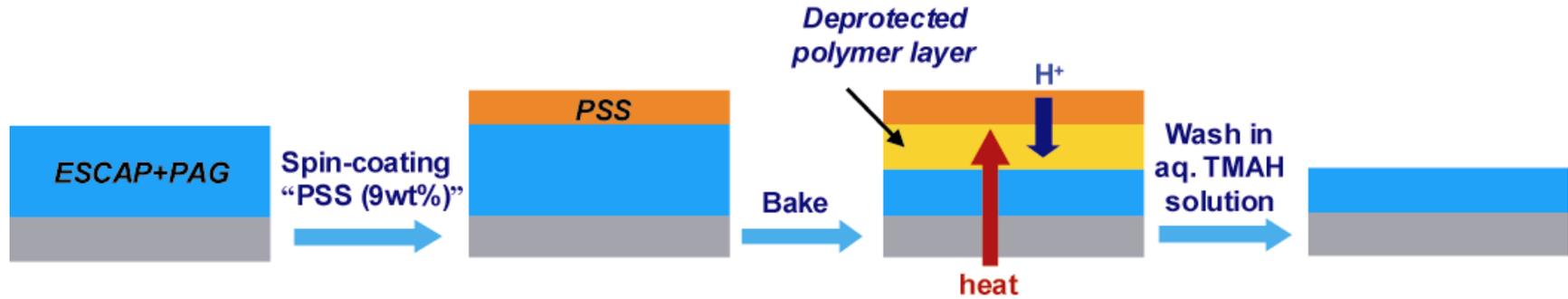


Aluminum



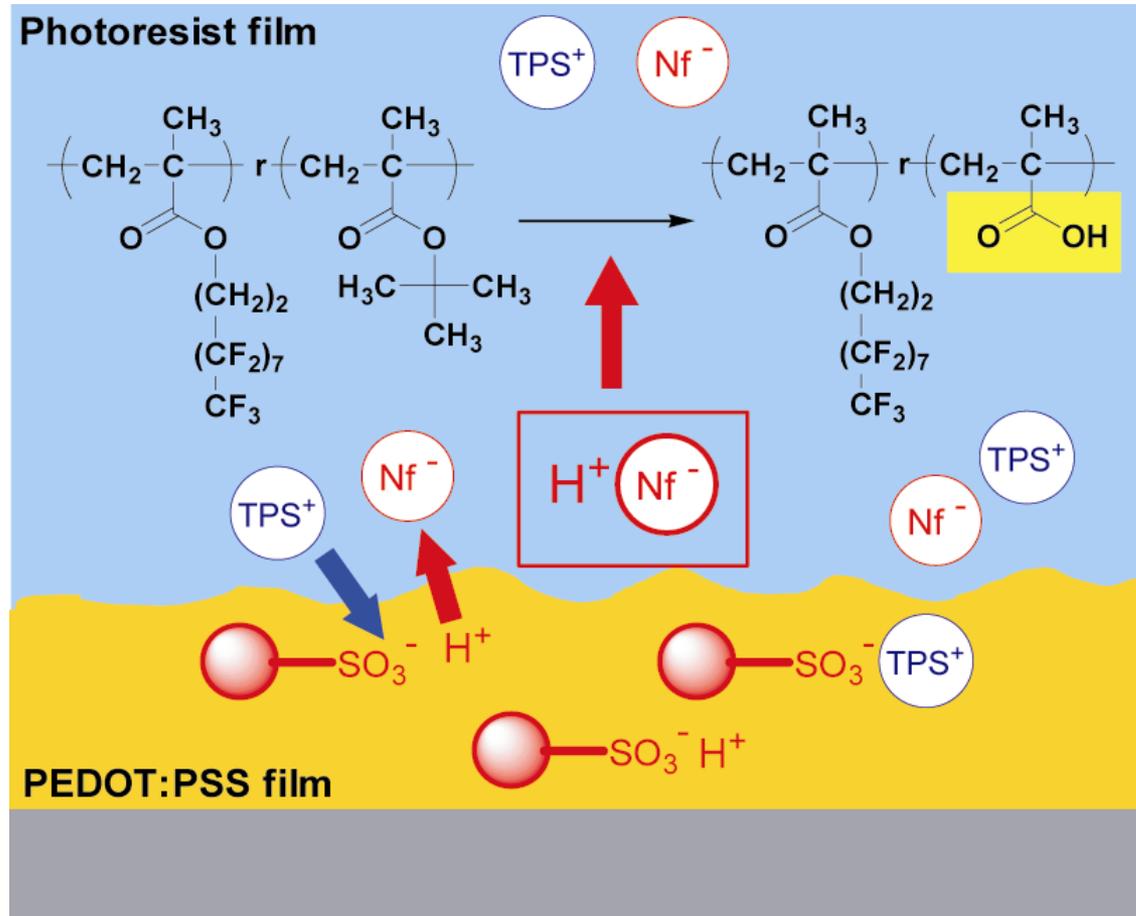
Acid-Diffusion in Conventional Resist

The same result was observed in case of ESCAP resist

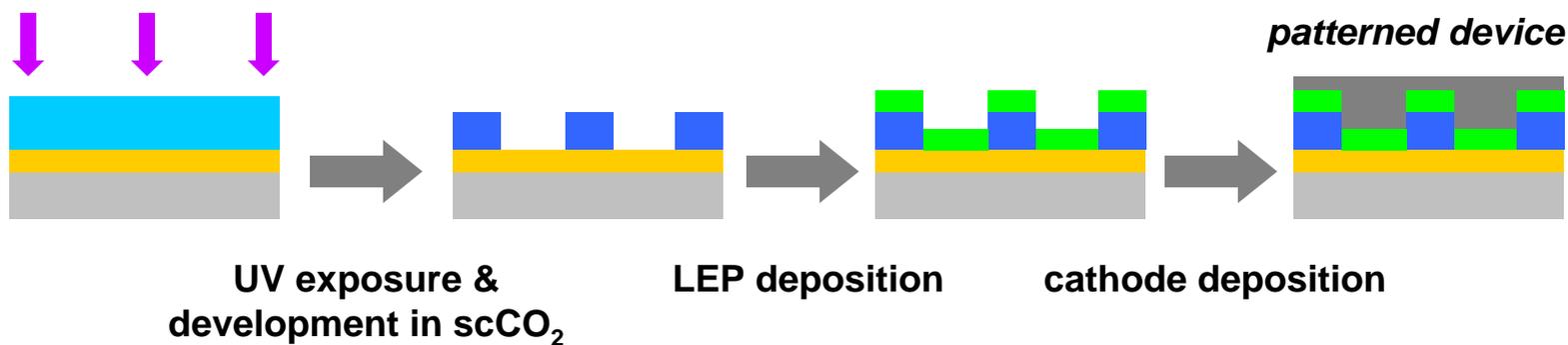


Acid-Diffusion: Proposed mechanism

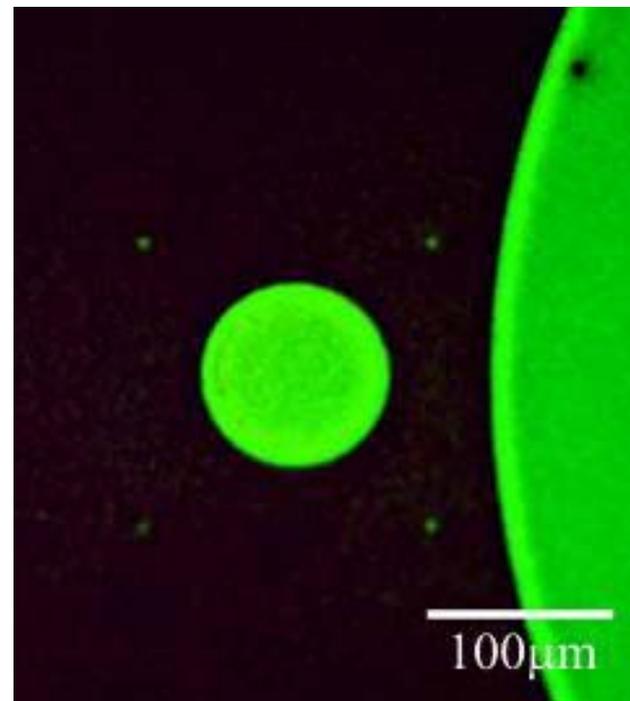
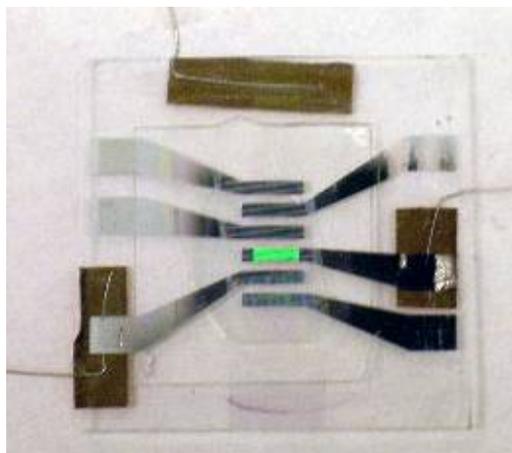
Ion exchange in the interfacial region has been suspected



Patterning OLED in $scCO_2$

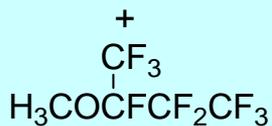


- | | |
|--|--------------------------|
| | - CsF/Al cathode |
| | - light emitting polymer |
| | - exposed resist |
| | - unexposed resist |
| | - PEDOT:PSS |
| | - ITO glass |

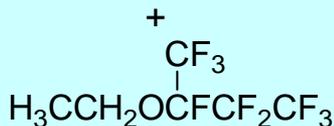
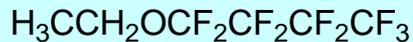


- 5 μ m fine features were realized
- luminous efficiency of ca. 22 cd/A

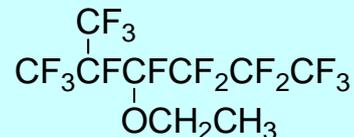
Hydrofluoroethers (HFEs)



HFE-7100 (bp 61 °C)



HFE-7200 (bp 76 °C)



HFE-7500 (bp 130 °C)

- Commercialized by 3M
- Benign to non-fluorinated organic electronic materials
- Environmentally safe (zero-ozone depletion potential)
- Facile recycling



EL device with $\text{Ru}(\text{bpy})_3(\text{PF}_6)_2$



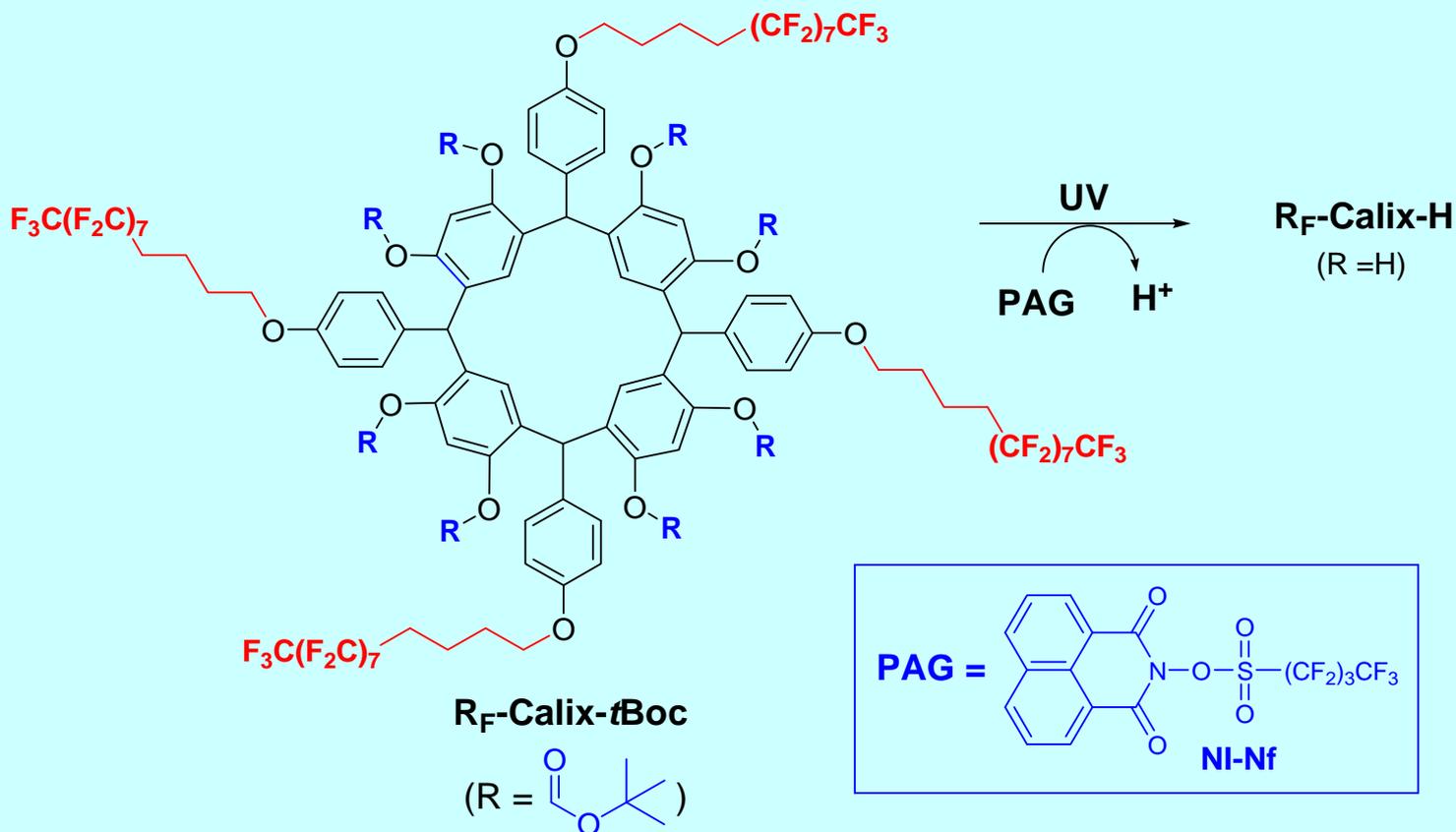
EL device with poly(dioctylfluorene)

HFEs are *orthogonal solvents* for organic electronic devices

A. A. Zakhidov, J.-K. Lee, H. H. Fong *et al.*, *Adv. Mater.*, 2008, 20, 3481.

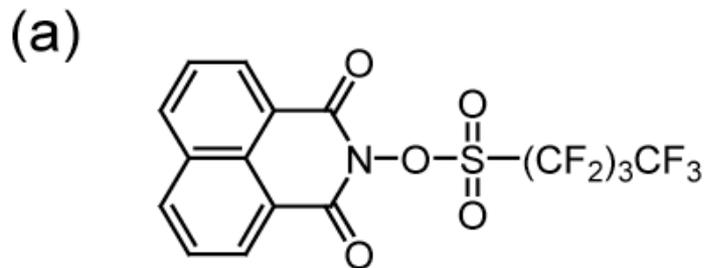
Molecular Resist Processable in HFEs

Chemically amplified molecular resist processable in HFEs

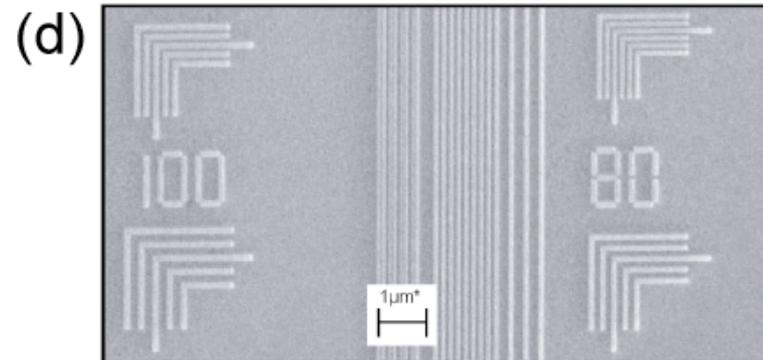
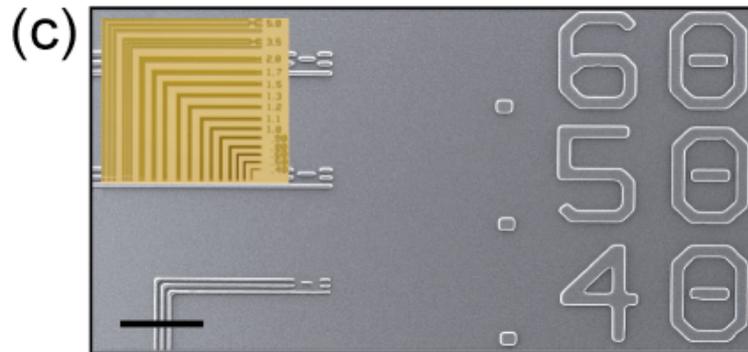
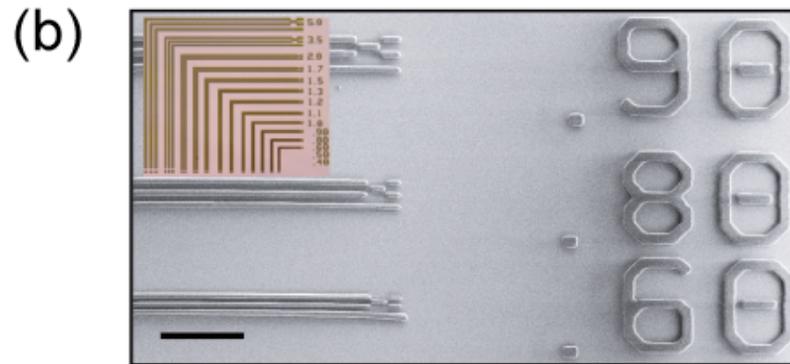


Lithographic Performance Evaluation

Spin-coated from HFE-7500 (4 parts) + PGMEA (1 part) mixture
 Pattern developed in HFE-7200



J. Photopolym. Sci. Technol., 2003, 16, 91.

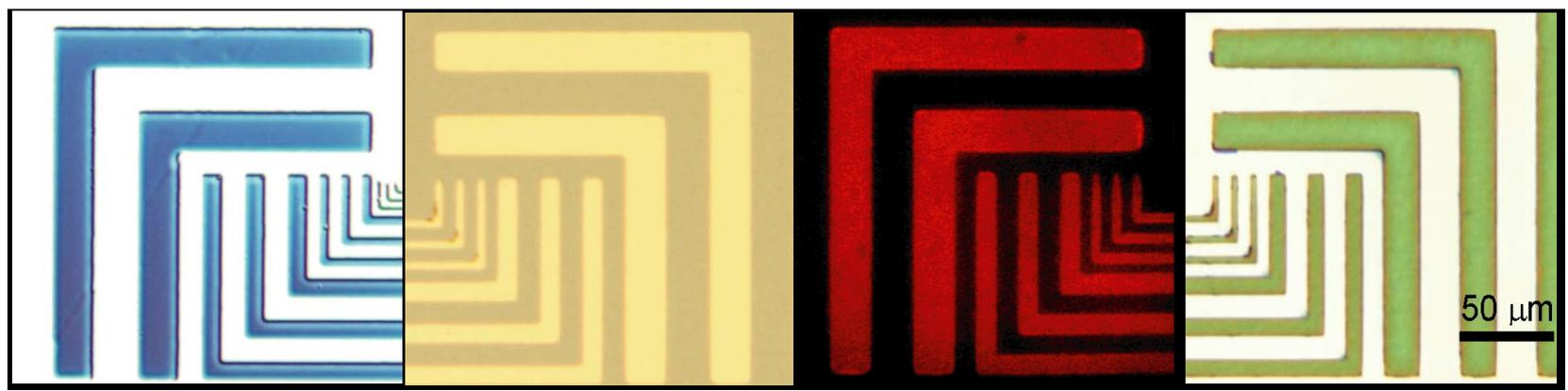
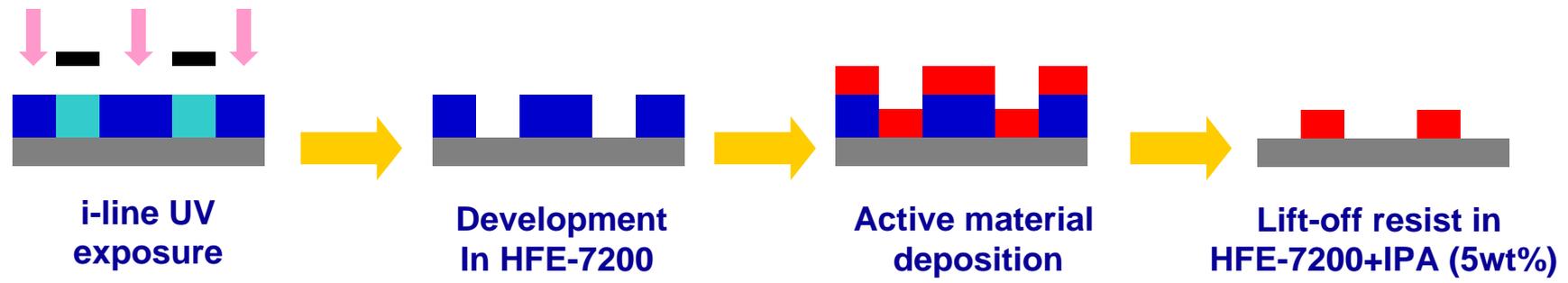


(a) Structure of a PAG. (b) Glass. (c) Polyimide-coated wafer (scale bars are 10 μm).
 (d) SEM image on Si under e-beam exposure (80 nm features).



Patterning Materials by Lift-off

Patterning of various electronic materials was successful



PEDOT:PSS (80 nm)

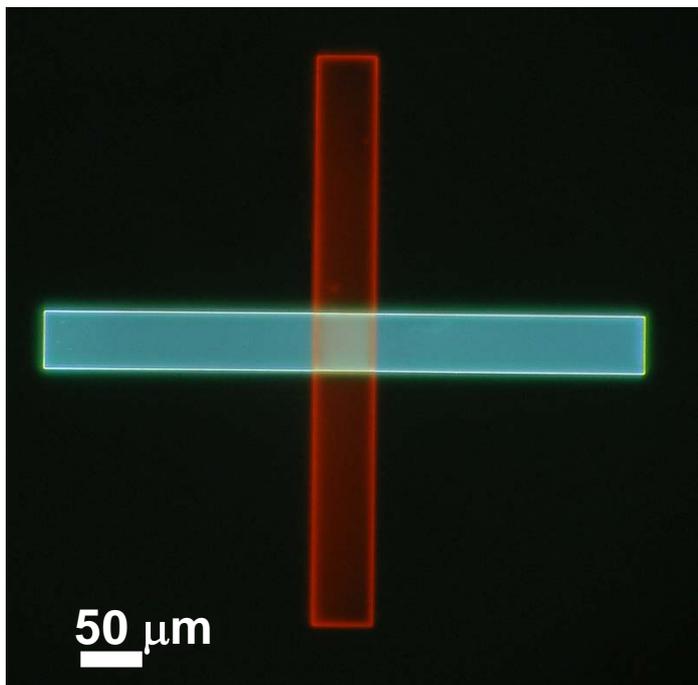
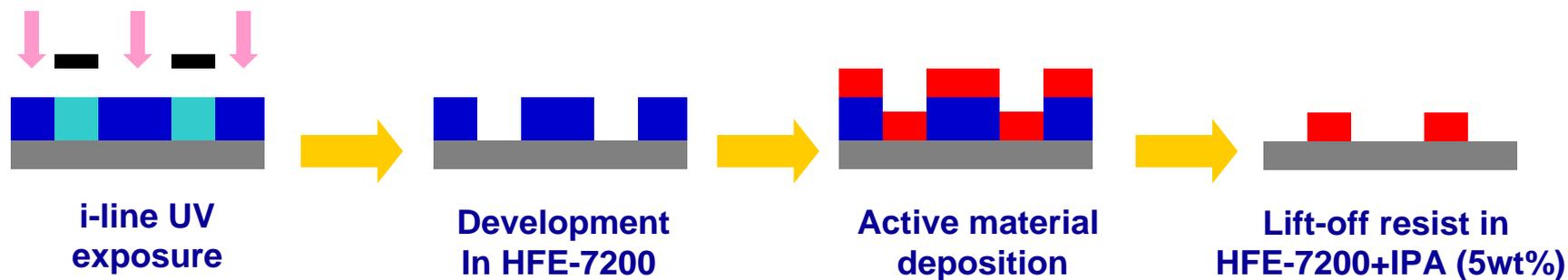
Gold (30 nm)

Ru(bpy)₃(PF₆)₂ (100 nm)

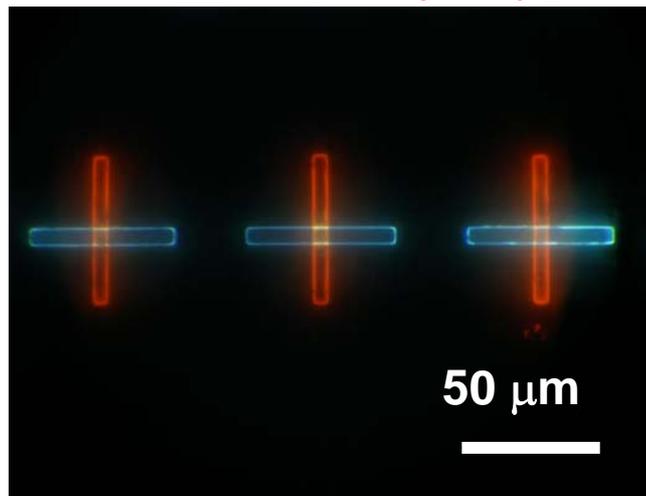
P3HT (30 nm)

Patterning Materials by Lift-off

Patterning of various electronic materials was successful

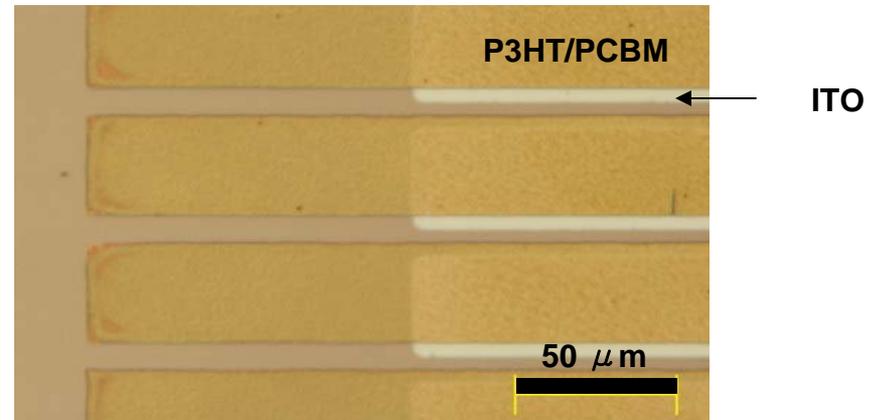
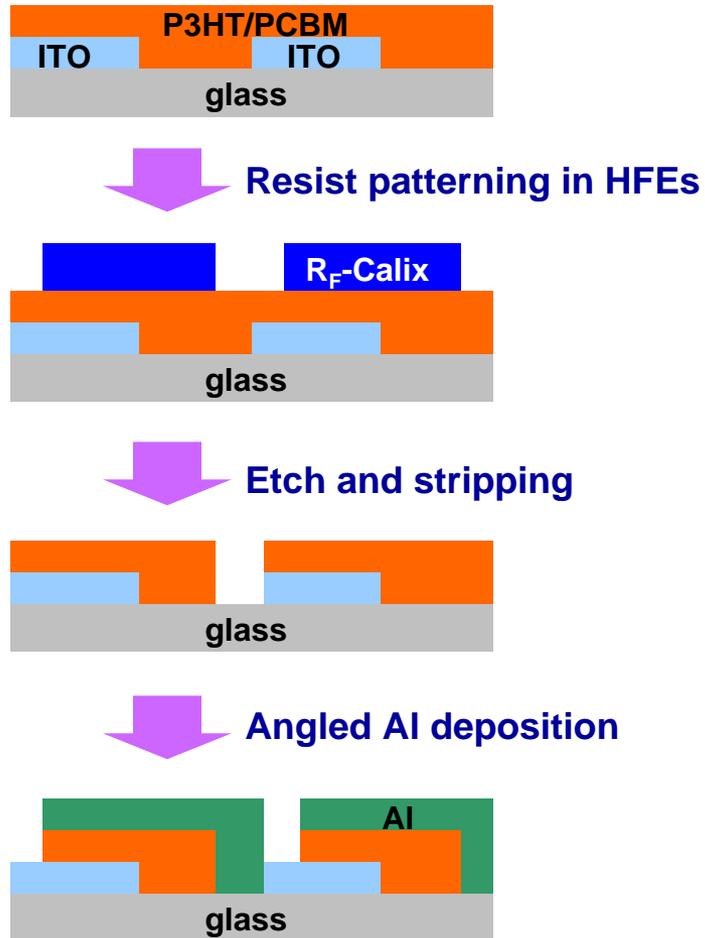


1st layer: polyfluorene (PF8)
 2nd layer: $\text{Ru}(\text{bpy})_3(\text{PF}_6)_2$



High Voltage Polymer Solar Cell

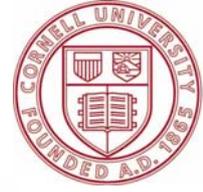
P3HT/PCBM solar cell patterned by orthogonal patterning



	Ours	Lit. ¹
Voc (V)	89.6	880
# cells	300	24,000
Voc/cell (V)	0.3	0.04
Jsc/cell (mA/cm ²)	4.2	0.34
FF	0.24	0.25
PCE (%)	0.31	0.008

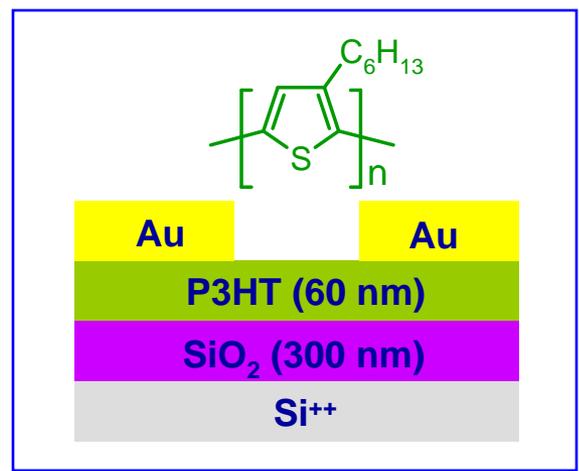
1. M. Niggemann *et al.*, *Adv. Mater.*, 2008, 20, 4055.

Y.-F. Lim, *et al.*, *J. Mater. Chem.*, 2009, 19, 5394.

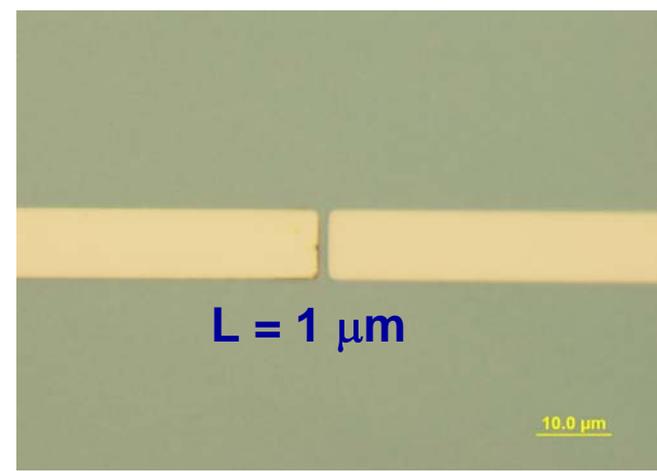


Application to Device Fabrication

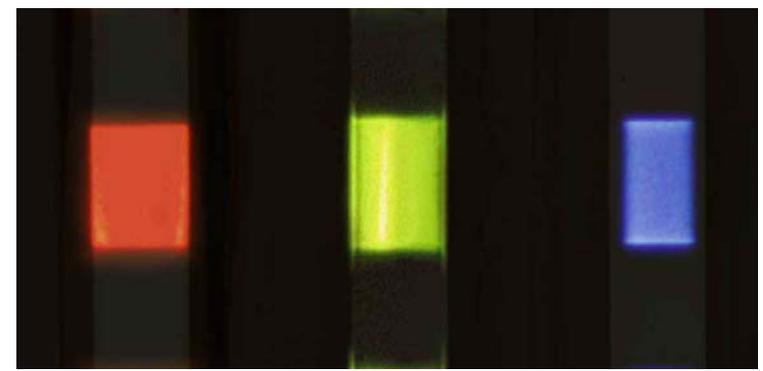
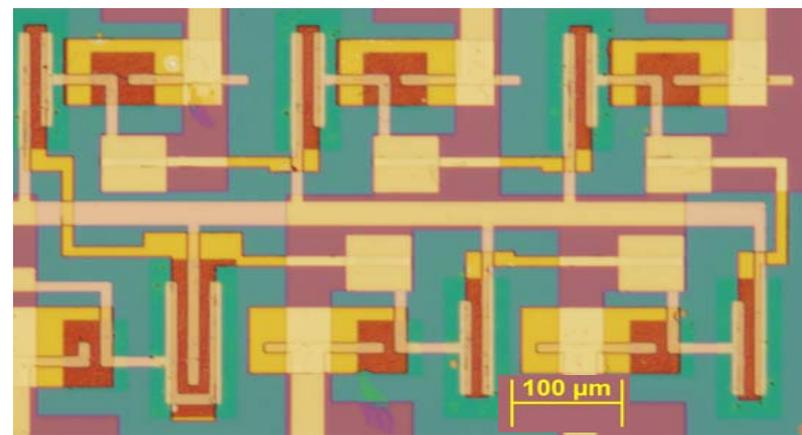
Organic FETs having top-contact source-drain geometry



Deposit Au contacts without using shadow masks



Mobility: $\mu_{\text{SAT}} = 0.01 \text{ cm}^2\text{V}^{-1}\text{s}^{-1}$
(0.45 for pentacene)

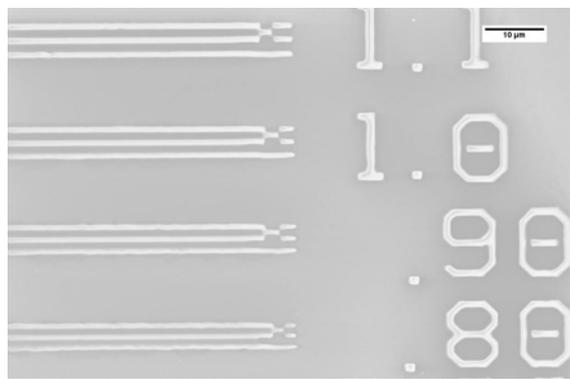
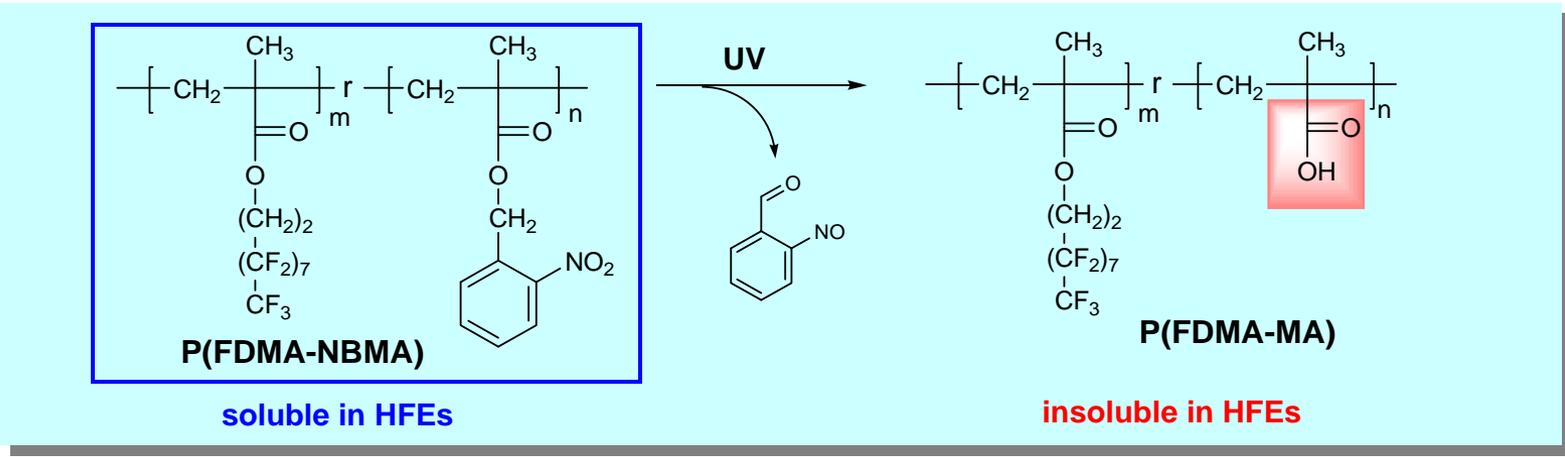


unpublished result



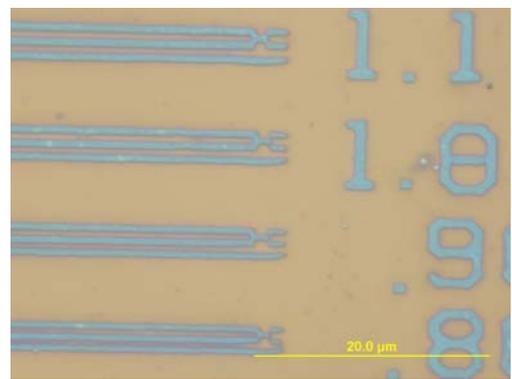
Orthogonal Patterning of PEDOT:PSS

Synthesis of acid-inert photoresist system specially designed for PEDOT:PSS patterning

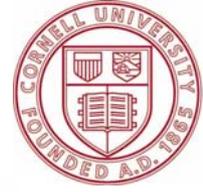


SEM image of P(FDMA-MA) on top of PEDOT:PSS film

O₂ plasma etch
→

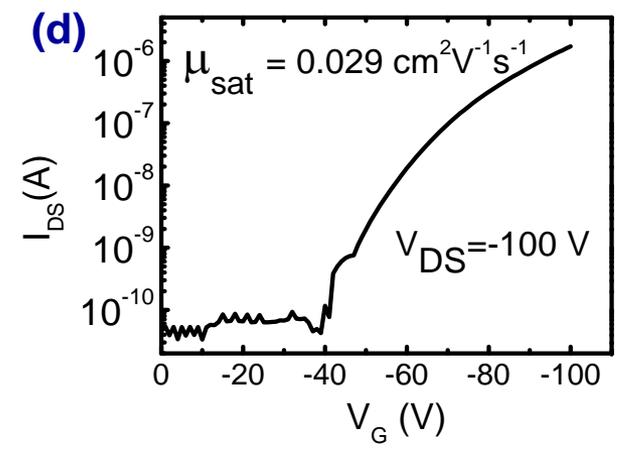
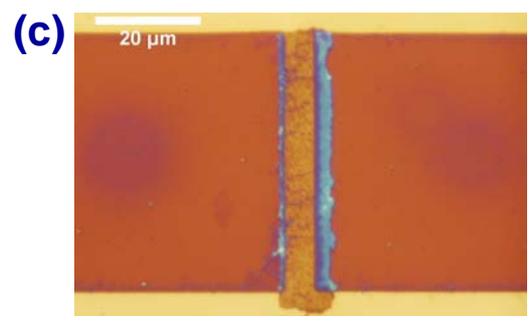
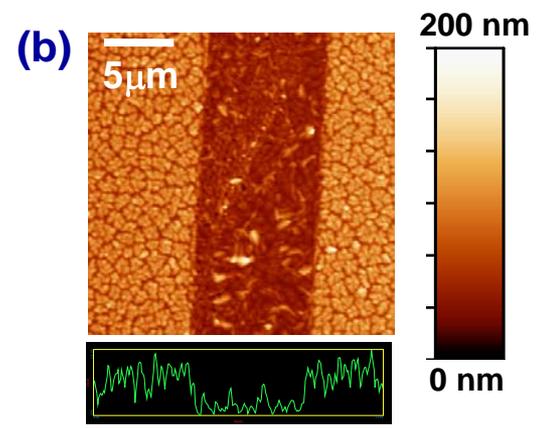
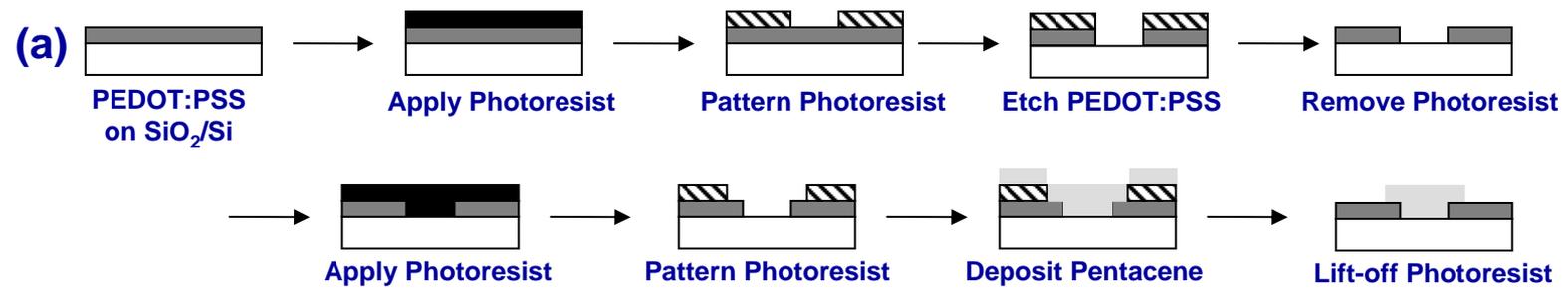


Optical image of patterned PEDOT:PSS film

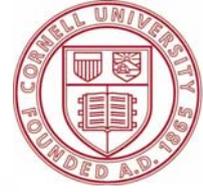


Orthogonal Patterning of PEDOT:PSS

Application to OTFT fabrication: PEDOT:PSS electrodes and pentacene active layer were patterned photolithographically



PEDOT:PSS/Pentacene bottom-contact OTFT (a) Schematic illustration of device fabrication, (b) AFM images of a 5 μm (width) x 50 μm (length) Pentacene channel between PEDOT:PSS electrodes (c) optical image of OTFT, (d) device performance plots

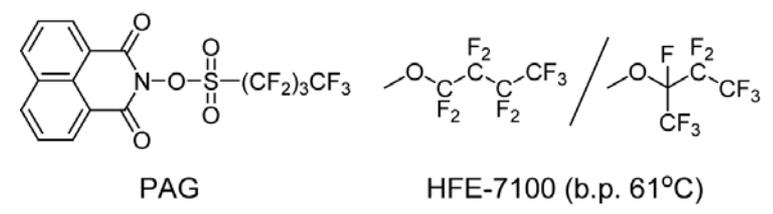
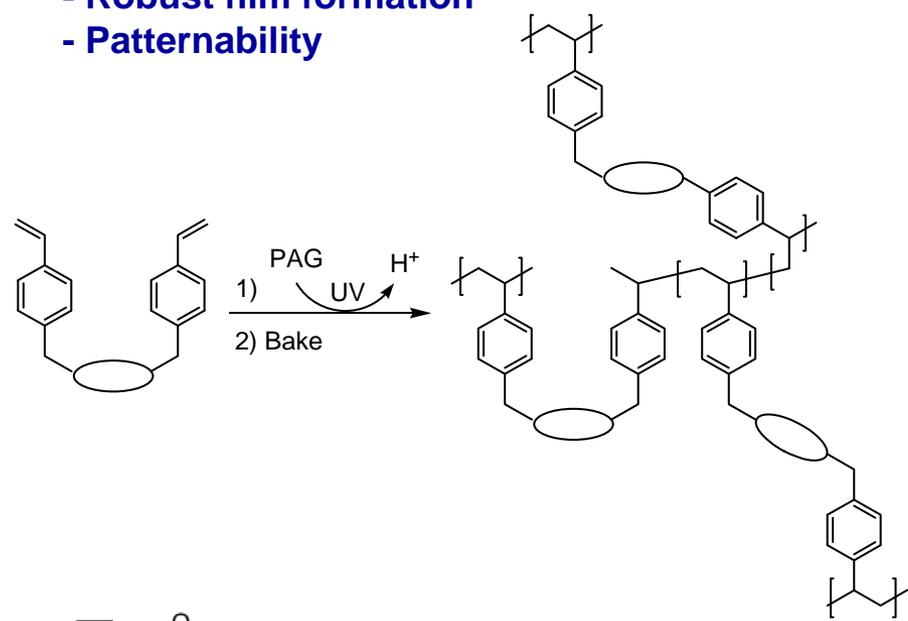


Patternable Low-k Materials in HFEs

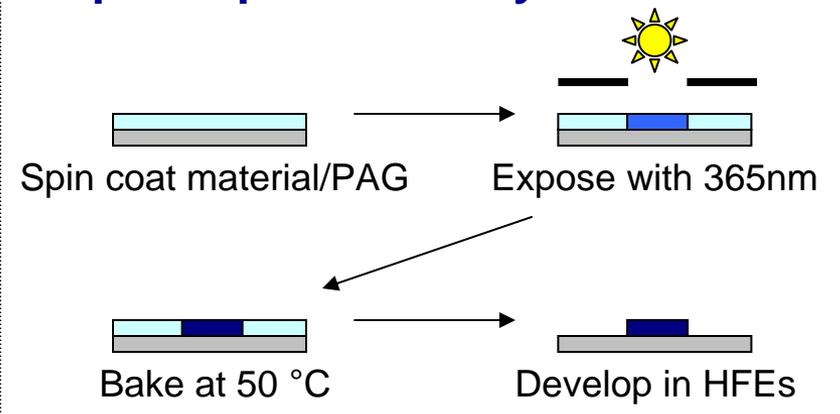
Photolithographic Patterning in HFEs

Crosslinking reaction

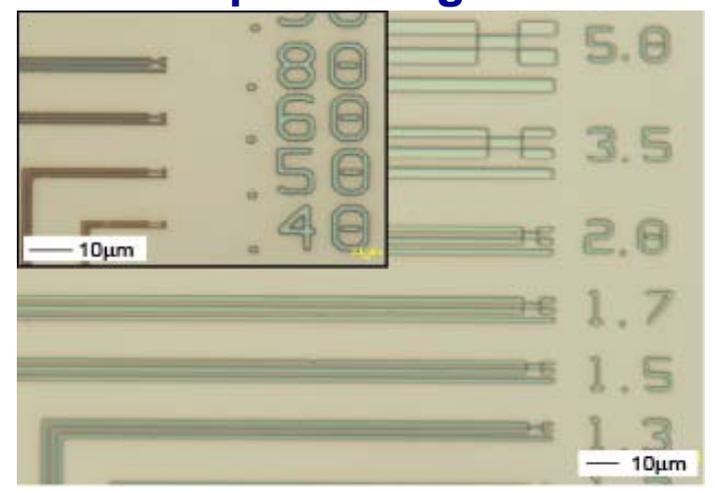
- Robust film formation
- Patternability



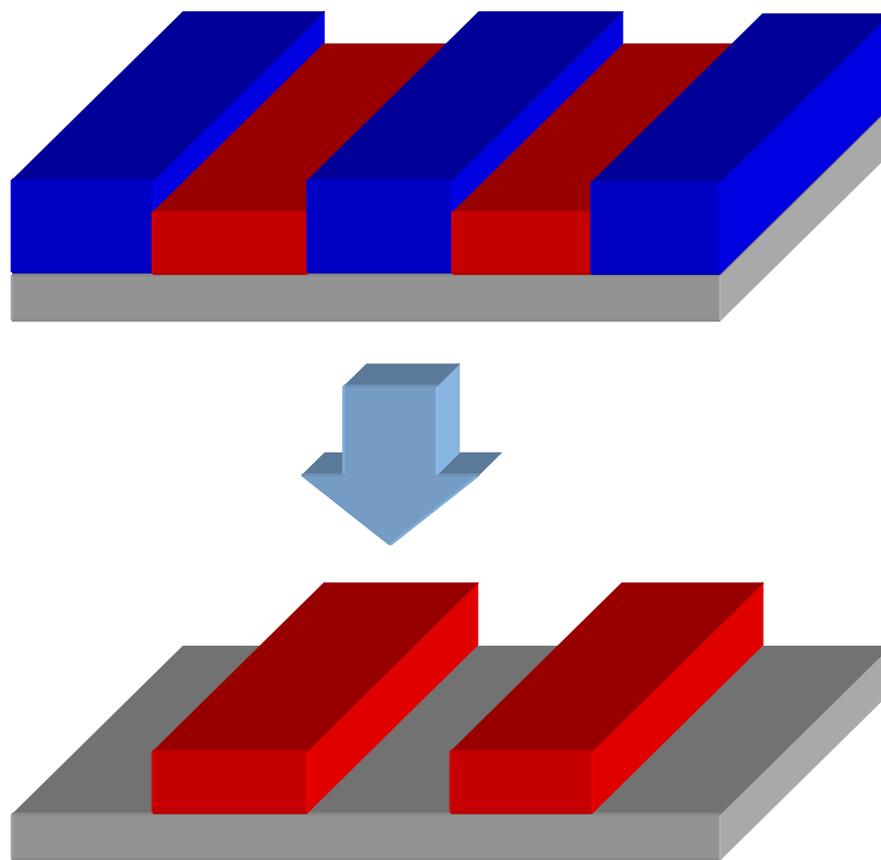
To prove patternability in HFEs



Successful patterning in HFE-7100

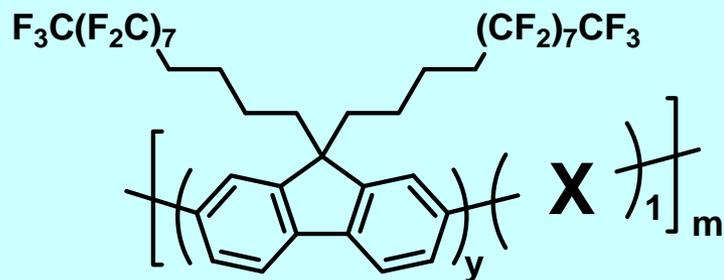


✓ **Patterning *Fluorinated Electronic Materials* employing *Conventional Photoresists* in Organic Solvents**

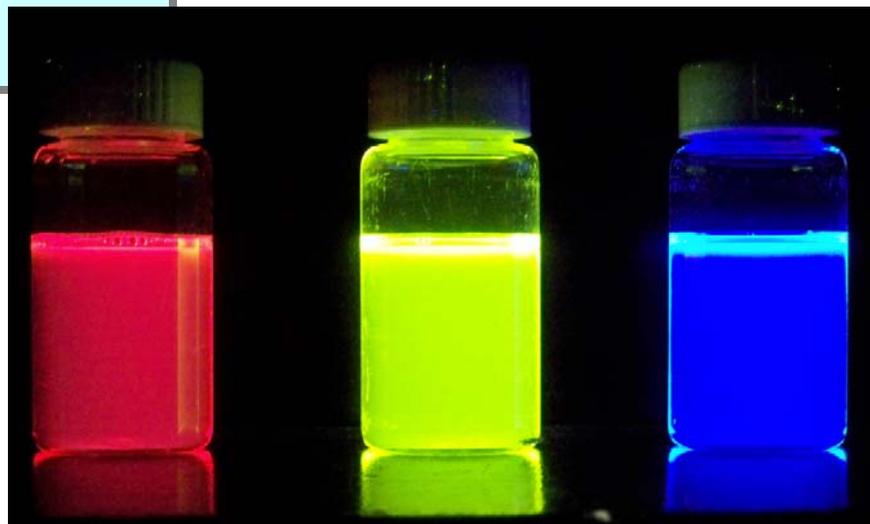


Semi-Perfluoroalkyl Polyfluorenes

Perfluoroalkyl polyfluorenes as blue light-emitting polymers



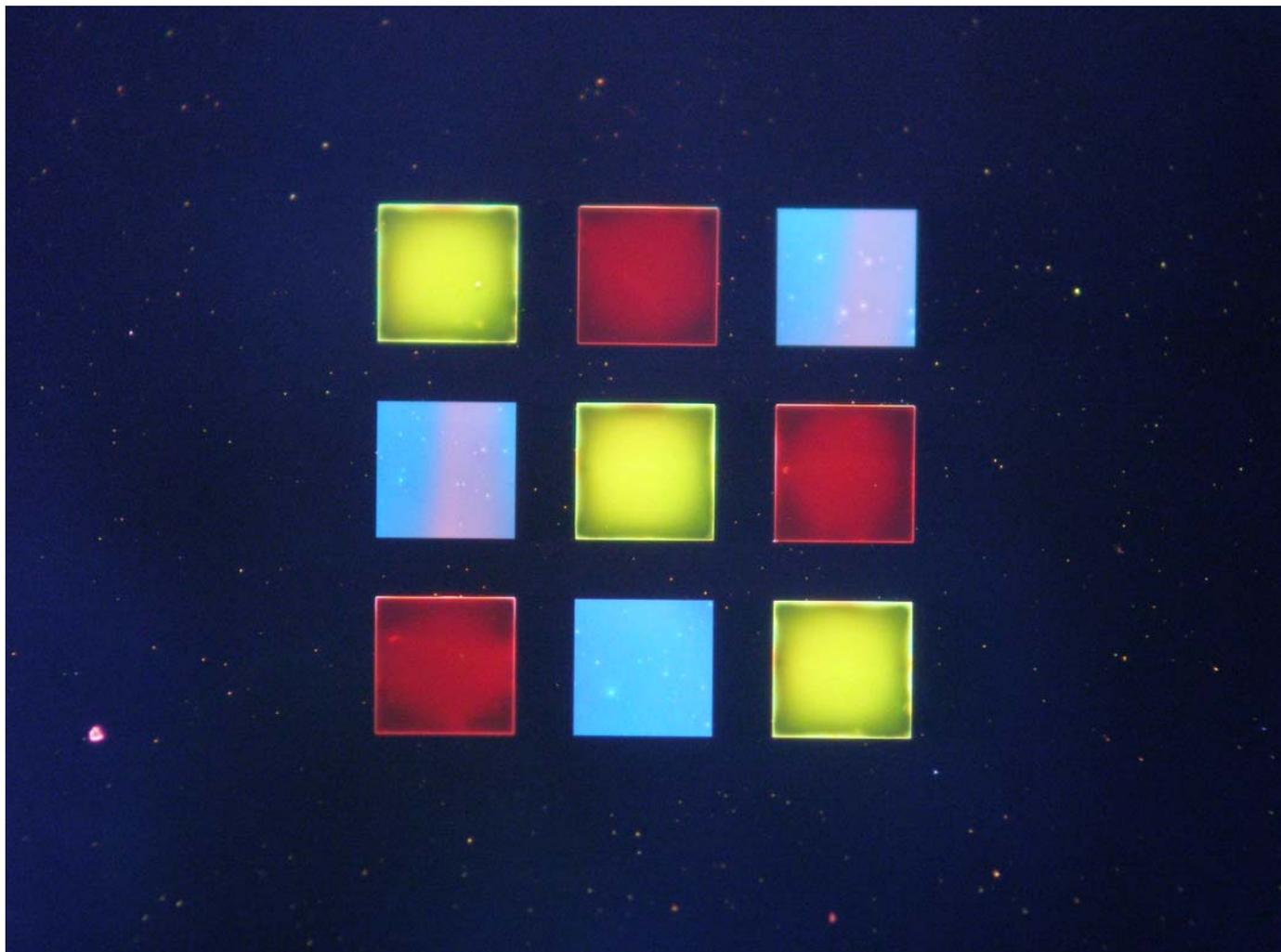
ca. 60% F content by weight



unpublished result

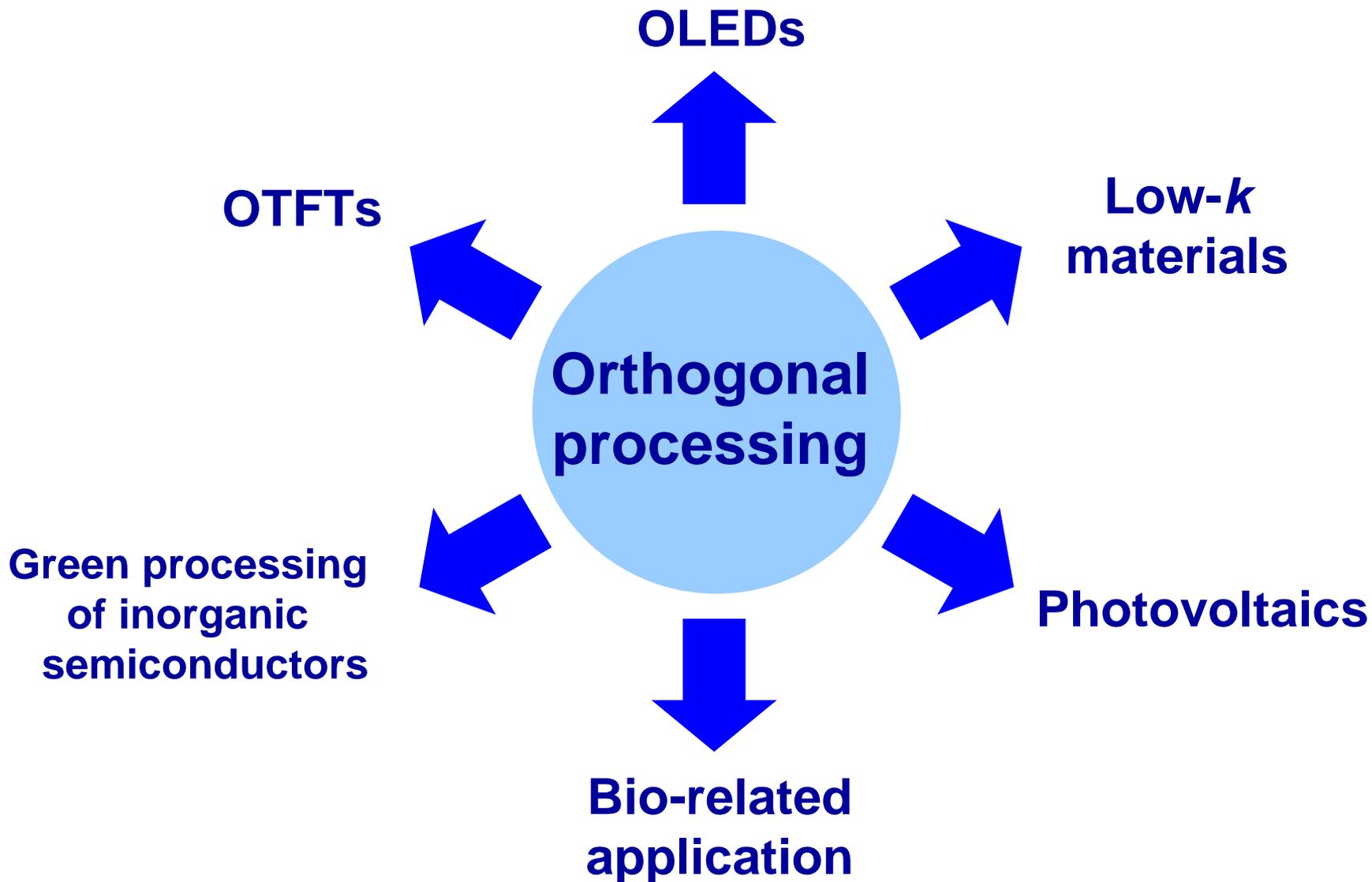
Application to Patterning

RGB patterning using conventional photoresists and organic solvents



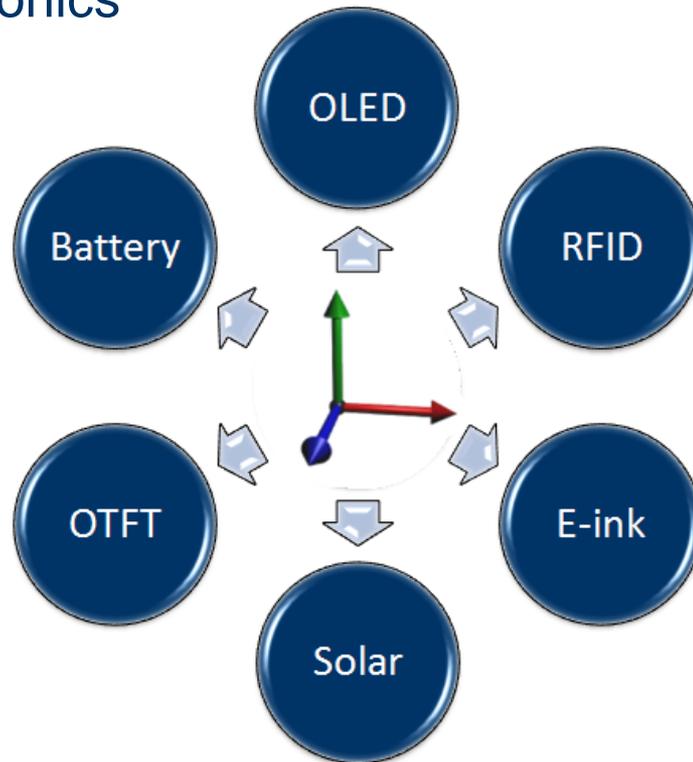


Potential of Orthogonal Processing



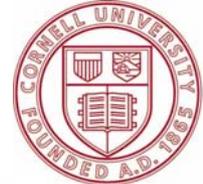
The Orthogonal Solution

- Patent-pending photoresist & process to manufacture organic electronics
 - Change photoresist chemistry to be compatible with sensitive organic systems
 - Enabling photolithography infrastructure to produce organic electronics



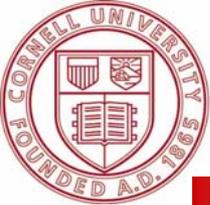
www.orthogonalinc.com





Summary

- ✓ **Concept of *Orthogonal Processing* for the patterning of organic electronic materials has been proposed**
- ✓ **HFEs have been identified as environmentally-friendly, chemically non-damaging solvents for *orthogonal processing***
- ✓ **Acid-sensitive perfluoroalkyl resorsinarene has been developed and employed successfully in OTFT and OLED fabrication**
- ✓ **Semi-perfluoroalkyl polyfluorenes have been synthesized and patterned with conventional photoresist and organic solvents**



Acknowledgement



Materials World Network Team at Cornell

**Alex Zakhidov, Priscilla Taylor, Hon Hang Fong, Eisuke Murotani,
John DeFranco, Margarita Chatzichristidi, Ha Soo Hwang
Prof. George Malliaras**

Materials World Network Team at Melbourne, Australia

**Georgia McCluskey, Wallace Wong
Prof. Andrew Holmes (Melbourne, Australia)**

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